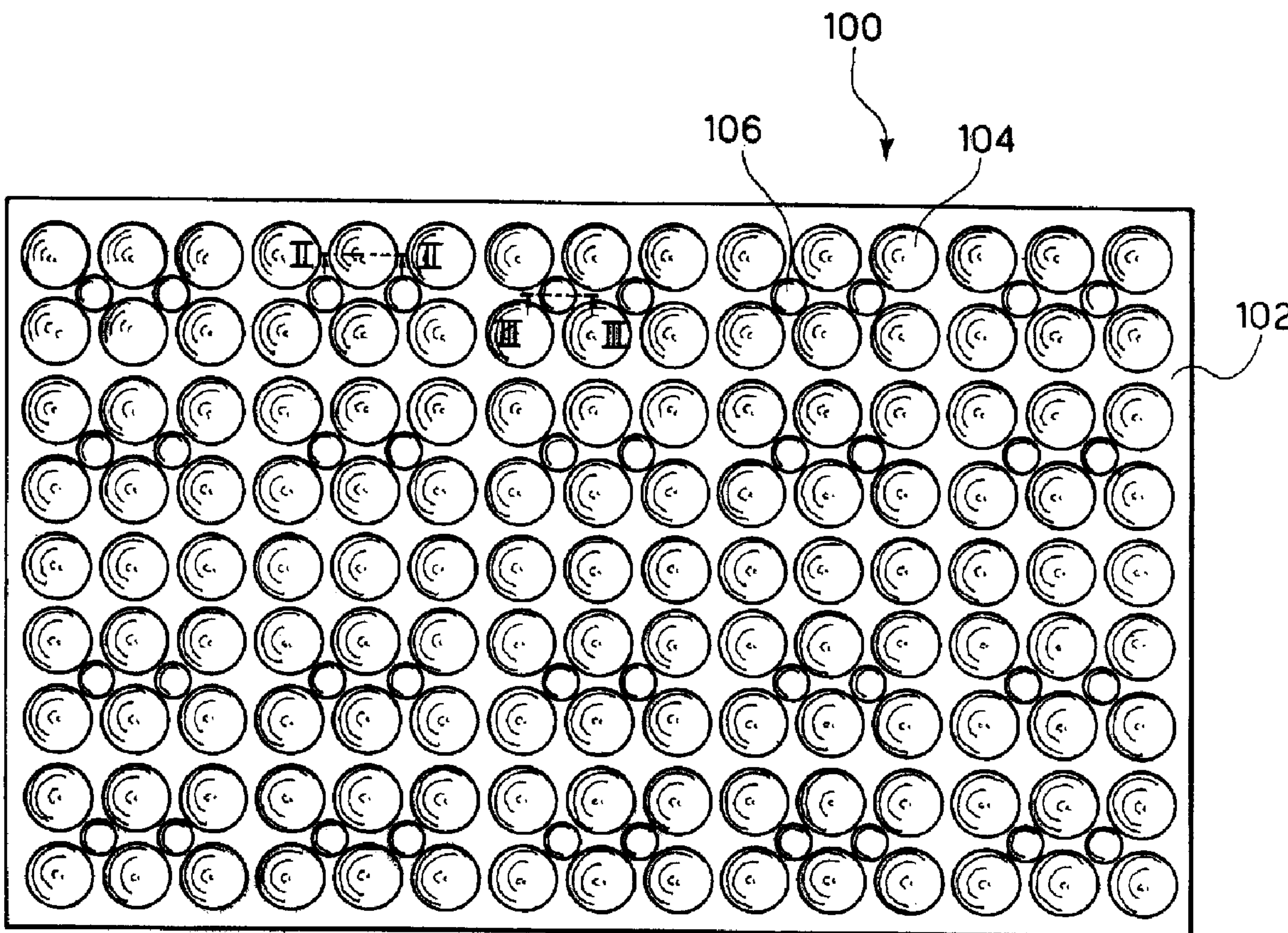




(22) **Date de dépôt/Filing Date:** 2007/12/06
 (41) **Mise à la disp. pub./Open to Public Insp.:** 2008/09/08
 (45) **Date de délivrance/Issue Date:** 2014/02/04
 (30) **Priorité/Priority:** 2007/03/08 (EP07425136.4)

(51) **Cl.Int./Int.Cl.** *A21B 5/02* (2006.01),
B29D 24/00 (2006.01), *A21D 13/08* (2006.01)
 (72) **Inventeurs/Inventors:**
FOGLIA, MICHELANGELO, IT;
MASSA, LUCIANO, IT
 (73) **Propriétaire/Owner:**
SOREMARTEC S.A., BE
 (74) **Agent:** MACRAE & CO.

(54) **Titre : FEUILLE DE GAUFRE, PLAQUE DE CUISSON ET METHODE D'UTILISATION CORRESPONDANTES**
 (54) **Title: WAFER SHEET, CORRESPONDING PRODUCTION PLATE AND METHOD OF USE**



(57) **Abrégé/Abstract:**

A wafer has a plane core part (102) and an array of hollowed formations (104) projecting for a given height with respect to the core part (102). The wafer also has a further array of formations (106) set between said hollowed formations (104) and projecting from the aforesaid core part (102) for a height (h) smaller than the height of the hollowed formations (104). The invention also relates to a plate that can be used for making said wafer, as well as a corresponding method of use.



ABSTRACT

A wafer has a plane core part (102) and an array of hollowed formations (104) projecting for a given height
5 with respect to the core part (102). The wafer also has a further array of formations (106) set between said hollowed formations (104) and projecting from the aforesaid core part (102) for a height (h) smaller than the height of the hollowed formations (104). The
10 invention also relates to a plate that can be used for making said wafer, as well as a corresponding method of use.

"Wafer sheet, corresponding production plate and method of use"

* * *

Field of the invention

5 The present invention relates to techniques for processing wafer products. The invention has been developed with particular attention paid to the production of wafer products comprising at least one shell having a hollow shape (for example, a hemispherical dome-shape) that is generally coupled to
10 a second shell having a hollow or plane shape, to form the product.

Description of the relevant art

15 Various patent documents describe techniques for producing the aforesaid wafer products with general hollowed conformation.

 These techniques have in common the fact of starting from a wafer comprising a core part (normally referred to as "carré"), in which the aforesaid
20 hollowed parts are formed. The hollowed parts are then separated from the starting wafer with an action of cutting.

 This action of cutting can be performed both in a direction orthogonal to the core part, as described in
25 EP-A-1 433 384, and by operating on an "equatorial" plane with respect to the hollowed parts, i.e., a plane that extends in the same direction as the core part of the wafers. In the latter case, the operation of cutting can be performed with different means: for
30 example, a band saw in the case of EP-A-0 054 229 or WO-A-97/48282, an array of disk saws in the case of EP-A-0 221 033, or a rotary tool substantially resembling a miller, in the case of EP-A-0 968 653. In the case of the solution described in EP-A-0 054 229 or WO-A-
35 97/48282, the action of cutting has the effect of

separating the hollowed parts from the plane core part or "carré". In the case of the solutions described in EP-A-0 221 033 and EP-A-0 968 653, the action of cutting also involves the plane core part, which is
5 made to crumble and is removed usually by suction means.

In any case, to perform the cutting operation properly it is necessary to ensure that the starting wafer is in a correct and exactly determined position
10 (corresponding in most instances to a height) with respect to the device that performs the cutting operation.

In the solution described in EP-A-0 054 229, the above result is obtained by arranging the starting
15 wafer in an alveolated mould, i.e., a mould provided with cavities that are to receive within them the hollowed parts of the wafers. These cavities are chosen in such a way as to have a depth at least slightly smaller than the maximum height of the hollowed parts.
20 When the wafer is located in the mould, the "polar" portions of the hollowed parts of the wafer rest against the bottom of the cavity of the mould (usually kept with the openings facing upwards) and, consequently, the plane part or "carré" of the wafer
25 comes to be raised (typically by a few millimetres) with respect to the front surface of the mould. There is thus formed, between the aforesaid front surface of the mould and the surface of the core part of the wafer facing it, the space of separation in which the cutting
30 device can intervene.

The above solution enables assurance of a high degree of precision in positioning the wafer, which normally is pressed against the mould by a conveying device, such as a motor-driven belt conveyor, whilst
35 the wafer advances with respect to the cutting device.

The pressure exerted on the wafer during the cutting operation guarantees, in fact, that the wafer is kept throughout its extension on a plane. In the case where no pressure were to be applied on the wafer, this would
5 tend to bend as a result of the action of the cutting means, preventing execution of a regular cut.

The above solution has the limitation represented by the fact that the mould used for supporting the wafer during the cutting operation (a mould that then
10 receives the hollowed parts separated from the core part) cannot be used for subsequent operations (for example, filling, etc.) performed on the hollowed parts of wafer. The reduced depth of the cavities of the mould means in fact that the mouth edges of the
15 hollowed parts project at least slightly with respect to the front surface of the mould. To carry out subsequent operations of treatment (such as filling or coupling of homologous hollowed parts with semicircular section so as to obtain, for example, a spherical wafer
20 shell), it is necessary to transfer the aforesaid hollowed parts into a mould provided with deeper openings so that the mouth edges of the hollowed parts of wafer will be aligned with the front surface of the mould. This operation of transfer constitutes a
25 considerable complication of the line lay-out.

In the solutions described in EP-A-0 221 033 and EP-A-0 968 653, this drawback is overcome by placing the wafer to be cut in alveolated moulds, the cavities of which are able to receive the hollowed parts of
30 wafer completely. To enable performance of the cutting operation, when the mould with the wafer within it advances towards the cutting device, pusher elements intervene on the polar portions of the hollowed parts penetrating through openings provided in the bottom
35 parts of the cavities of the mould and raising the

wafer to the height desired for proper interaction with the cutting device.

The above solution, which has been used with full satisfaction and success for many years, imposes the need, however, to associate to the cutting device the raising mechanism described previously. This mechanism can end up being even rather complex, also considering that usually it is necessary to set a raising element for each hollowed part. In addition, the raising element must be able to provide a gripping portion (typically suction) on the hollowed part on which it intervenes.

Object and summary of the present invention

The object of the present invention is to provide a solution that, maintaining the positive aspects of the solutions described previously, will avoid the drawbacks linked to said preceding solutions, as outlined above.

According to the present invention, this object is achieved thanks to a wafer having the characteristics recalled specifically in Claim 1. Advantageous developments of the invention form the subject of the subclaims. The invention also relates to an oven plate for producing said wafer, as well as a corresponding method of use.

The claims form an integral part of the disclosure of the invention provided herein.

Brief description of the annexed figures

The invention will now be described, purely by way of non-limiting example, with reference to the annexed plate of drawings, in which:

- Figure 1 is a plan view of a wafer as described herein;

- Figure 2 illustrates a partial cross-sectional view according to the line II-II of Figure 1;

- Figure 3 illustrates a partial cross-sectional view according to the line III-III of Figure 1;

- Figure 4 is a schematic illustration of the modalities of treatment of the wafer described herein;
5 and

- Figure 5 is a partial cross-sectional view of a mould (plate) prearranged to form the wafer described herein.

Detailed description of exemplary embodiments

10 The solution forming the subject of the present application will be described with reference, by way of example, to the production of foodstuffs comprising a spherical wafer shell obtained via the frontal juxtaposition of two half-shells having a substantially
15 hemispherical shape.

Products of this type are known in the art. In this connection, reference may be made to the confectionery products sold under the trademarks Ferrero Rocher® or Confetteria Raffaello® of the companies of the Ferrero
20 group. The same companies also sell other products (see, for example, the confectionery products sold under the trademarks Kinder Maxi King®, Happy Hippo®) comprising half-shells once again having a hollowed shape but different from the hemispherical one.

25 These half-shells can be produced by resorting to the techniques of cutting in the "equatorial" plane described in the various documents already cited in the introductory part of the present description.

The half-shells in question (it is to be recalled
30 that the reference to hemispherical half-shells herein has a purely exemplary character in so far as what is described and illustrated herein is applicable in general to hollowed parts having any shape and dimensions) are obtained starting from a wafer 100 in
35 which it is in general possible to distinguish:

- a core plane (commonly referred to as "carré")
102; and

- an array of hemispherical (or, in general,
hollowed) formations 104; these formations, which are
5 illustrated at an enlarged scale in a cross-sectional
view in Figure 2, are initially integral with the core
plane 102 and are then to be separated therefrom with
an operation of cutting carried out in general in a
direction parallel to the direction of extension of the
10 core plane 102.

An important characteristic of the solution
described herein lies in the fact that the wafer 100
has a further array of approximately hollowed
formations, designated by 106. These further
15 formations, one of which is illustrated at an enlarged
scale in a cross-sectional view in Figure 3, project
from the core plane 102 always on the same side as the
one from which the hollowed formations 104 project.

The array of the formations 106 is staggered with
20 respect to the array of the formations 104, in the
sense that the formations 106 are arranged in areas
corresponding to parts and regions of the core part 102
in which the hollowed formations 104 are not present.
The formations 106 can be ordered in rows, or else in
25 rows and columns. Furthermore, according to one
embodiment of the invention, the formations 106 can be
ordered in pairs so that the wafer will comprise groups
formed by a pair of the hollowed formations 104 and a
pair of the formations of the further array 106
30 arranged at the vertices of a quadrilateral, such as a
rhombus.

The formations 106 thus have a depth (height)
smaller than the hollowed formations 104. Just to
clarify the description (without this implying any
35 limitation of the scope of the invention), the

formations 106 have a height h (i.e., the amount they protrude with respect to the surface of the core part 102) correlated to the depth of the hollowed formations 104 and preferably comprised between 0.5 mm and 10 mm. Preferably the height h is approximately equal to the thickness of the core part 102 (a thickness that is typically in the region of 1- 3 mm). In a preferred way, the formations 106 have a height h substantially equal to or larger than the thickness of the core part 102.

In a particularly preferred way, the formations 106 have a general "mesa" configuration, i.e., they present, if viewed from the side of their concavity, basically as trays with a plane bottom wall (parallel to the general plane of extension of the core part 102); in a further particularly preferred way, the formations 106 substantially resemble circular buttons having a diameter in the region of 10 mm.

The formations 106 could on the other hand have different shapes and present, for example, a general cup-like or V-shaped conformation.

When, as schematically illustrated in Figure 4, the wafer 100 is set in an alveolated mould 110 so as to proceed to the cutting operation (according to the modalities described in the documents Nos. EP-A-0 054 229, WO-A-97/48282, EP-A-0 221 033, and EP-A-0 968 653), the net effect of the presence of the formations 106 is to cause, even when the cavities of the mould 110 are able to receive the hollowed parts 104 completely, the formations 106 to bear upon the front surface of the mould 110 and keep the core part 102 raised by an amount G equal to their height, designated by h .

In this way, it is possible to establish the desired distance between the core part (or "carré") 102

and the front surface of the mould 110 to perform the operation of cutting properly using a tool T (whatever this may be).

In particular, the formations 106 constitute, for the core part 102, a sort of array of feet for resting on the front surface of the mould 110 such as to keep the core part 102 (in particular when the core part 102 is pressed towards the mould 110, for example by a pressure pad P) at a constant height, throughout the surface development of the wafers 100, with respect to the front surface of the mould 110. This arrangement is guaranteed also in the case where (as occurs normally as a result of the very mechanism of production of the wafer 100) the core part 102 has internal stresses that tend to cause it to bend.

For this purpose, during the step of cutting, the wafers 100 are kept under pressure against the moulds 110 (for example, via the pressure pad) so as to prevent any bending and enable cutting to be performed at a controlled and desired height throughout the area of the wafer.

With the solution described herein, it is possible to use a mould 110 that is able to receive the hollowed parts 104 properly once separated from the core part 102 by the cutting operation, without there being necessary the transfer into moulds different from the one used for performing the cutting operation.

At the same time, it is possible to do without the mechanism for raising the wafer, which, by acting with pusher elements that penetrate through the polar parts (that are to be perforated) of the hollowed parts of the receiving mould, raise the wafer, bringing it to the desired height for intervention of the cutting device.

In the solution described herein, this effect of

raising is instead provided exclusively by the formations 106, which, moreover, are eliminated (or at least separated from the core part 102) precisely by the same action of cutting that leads to the separation
5 of the hollowed parts 104 (see in this connection Figure 4).

In any case, the array of the formations 106 is in a number and presents a distribution of formations such as to distribute uniformly over the front surface of
10 the mould 110, functioning as contrast surface, the pressure exerted on the wafer 100 - for example, via the pressure pad P - during performance of the cutting operation (whatever the way in which this is done), preventing bending of the wafer 100 in any area
15 thereof.

A wafer 100 having the characteristics referred to can be obtained, according to known criteria, with an oven plate such as the plate 200 illustrated in Figure 5.

20 The oven plate for production of the wafers 200 in question comprises two complementary parts, i.e., a plate 202 and a counter plate 204 that have surface morphologies such as to reproduce in a complementary way the hollowed formations 104 and the formations 106
25 that are to constitute the "buttons" or "feet" that keep the wafer 100 raised during the cutting operation described previously.

In this connection, the experiments conducted by the present applicant show that the "mesa" or tray-shaped conformation with plane bottom part, as may be
30 inferred from the annexed plate of drawings, is preferential for the purposes of carrying out the operation of baking of the wafer batter contained between the plate 202 and the counter plate 204 that
35 leads to the formation of the wafer 100. The present

applicant has in fact been able to note that different conformations (for example, formations 106 that reproduce - on a smaller scale - the same conformation as that of the formations 104) can give rise in some circumstances to a wafer 100 with a differentiated degree of baking in an area corresponding to the formations 106 and the formations 104. In some cases, this difference can prove undesirable (for example, owing to an at least partial burning of the formations 106) and is thus to be avoided.

It will be appreciated that the solution described herein is applicable also in the case where the wafer 100 presents differentiated thicknesses in areas corresponding to the core part 102 and the formations 104, as described, for example, in WO-A-97/48282. The formations 106, which project from the core part 102 and form, on the side opposite to the projection, a cavity in the core part 102 itself, can also be used to form a coupling having a shape of the male and female type between portions of wafer that are to be coupled together when the operations of filling or the like are carried out. In this case, it may be envisaged that the formations 106, herein all represented as projecting from the core part 102 on the same side as that on which the formations 104 project, may project on opposite sides of the core part 102 itself.

It follows that, without prejudice to the principle of the invention, the details of construction and the embodiments may vary widely with respect to what is described and illustrated herein purely by way of non-limiting example, without thereby departing from the scope of the invention, as defined by the annexed claims.

CLAIMS

1. A method for making wafer bodies having a general hollowed conformation, the method comprising
5 the operations of:

- providing a wafer (100) having a plane core part or "carré" (102) and an array of hollowed formations (104) projecting for a given height with respect to said core part (102);

10 - setting said wafer (100) in an alveolated mould (110) having a front surface, in which cavities are made for receiving said hollowed formations (104) of the wafer, and

- subjecting said wafer (100) to an action of
15 cutting (T) that separates said hollowed parts (104) from said core part (102)

characterised in that it comprises the operation of:

- providing said wafer (100) with a further array
20 of formations (106) set between said hollowed formations (104) and projecting from said core part (102) on the same side as said hollowed formations (104) for a height (h) smaller than said given height of said hollowed formations (104),

25 - setting said wafer (100) in said alveolated mould (110) with formations (106) of said further array resting on said front surface of said mould (110) so as to keep said core part (102) at a distance from said front surface of the mould by a gap (G) of a width
30 defined by the height (h) of said formations (106) of said further array.

2. The method according to Claim 1, in which said cutting operation is performed in said gap (G) of a width defined by the height (h) of said formations
35 (106) of said further array.

3. The method according to Claim 1, in which said cutting operation (T) leads to crumbling of said core part (102).

5 4. A wafer for carrying out the method according to any one of Claims 1 to 3, said wafer having a plane core part or "carré" (102) and an array of hollowed formations (104) projecting for a given height with respect to said core part (102), said wafer having a
10 further array of formations (106) set between said hollowed formations (104) and projecting from said core part (102) on the same side as said hollowed formations (104) for a height (h) smaller than said given height of said hollowed formations (104).

15 5. The wafer according to claim 4, in which the formations of said further array (106) have a height (h) correlated to the depth of the hollowed formations (104), preferably comprised between 0.5 mm and 10 mm.

20 6. The wafer according to one of the preceding claims 4 or 5, in which said further array of formations (106) comprises formations (106) arranged in rows and/or columns.

25 7. The wafer according to any one of the preceding claims 4 to 6, in which the formations of said further array (106) have a general tray-like conformation with a plane bottom wall.

 8. The wafer according to any one of Claims 4 to 7, in which the formations of said further array (106) have a general cup-like conformation.

30 9. The wafer according to any one of Claims 4 to 8, in which the formations of said further array (106) are generally V-shaped.

35 10. The wafer according to any one of the preceding claims 4 to 9, in which said core part (102) has a given thickness and in which the height (h) of the

formations of said further array (106) is substantially equal to or larger than said given thickness.

11. The wafer according to any one of the preceding claims 4 to 10, in which said hollowed formations (104) have a height comprised between 1 and 30 mm.

12. The wafer according to any one of the preceding claims 4 to 11, in which the formations (106) of said further array are in a number and have a distribution such as to distribute uniformly over a contrast surface (110) a pressure (P) exerted on the wafer, preventing bending of the wafer itself in any area thereof.

13. A plate for making wafers for carrying out the method according to any one of Claims 1 to 3, said plate comprising complementary half-plates (202, 204) jointly defining between them a space for receiving a batter which, after baking, is to constitute said wafer, in which said space for the batter has a further array of formations (106) set between said hollowed formations (104) and projecting from said core part (102) on the same side as said hollowed formations (104) for a height (h) smaller than said given height of said hollowed formations (104).

14. The plate according to Claim 13 to 14, in which the formations of said further array (106) have a height (h) correlated to the depth of the hollowed formation (104), preferably comprised between 0.5 mm and 10 mm.

15. The plate according to one of Claims 13 or 14, in which said further array of formations (106) comprises formations (106) arranged in rows and/or columns.

16. The plate according to any one of Claims 13 to 15, in which the formations of said further array (106) have a general tray-like conformation with a plane bottom wall.

17. The plate according to any one of Claims 13 to 16, in which the formations of said further array (106) have a general cup-like conformation.

18. The plate according to any one of Claims 13 to 5 17, in which the formations of said further array (106) are generally V-shaped.

19. The plate according to any one of the preceding Claims 13 to 18, in which said core part (102) has a given thickness and in which the height (h) of the 10 formations of said further array (106) is substantially equal to or larger than said given thickness.

20. The plate according to any one of the preceding Claims 13 to 19, in which said hollowed formations (104) have a height comprised between 1 and 30 mm.

15 21. The plate according to any one of the preceding Claims 13 to 20, in which the formations (106) of said further array are in a number and have a distribution such as to distribute uniformly over a contrast surface (110) a pressure (P) exerted on the wafer preventing 20 bending of the wafer itself in any area thereof.

FIG-1

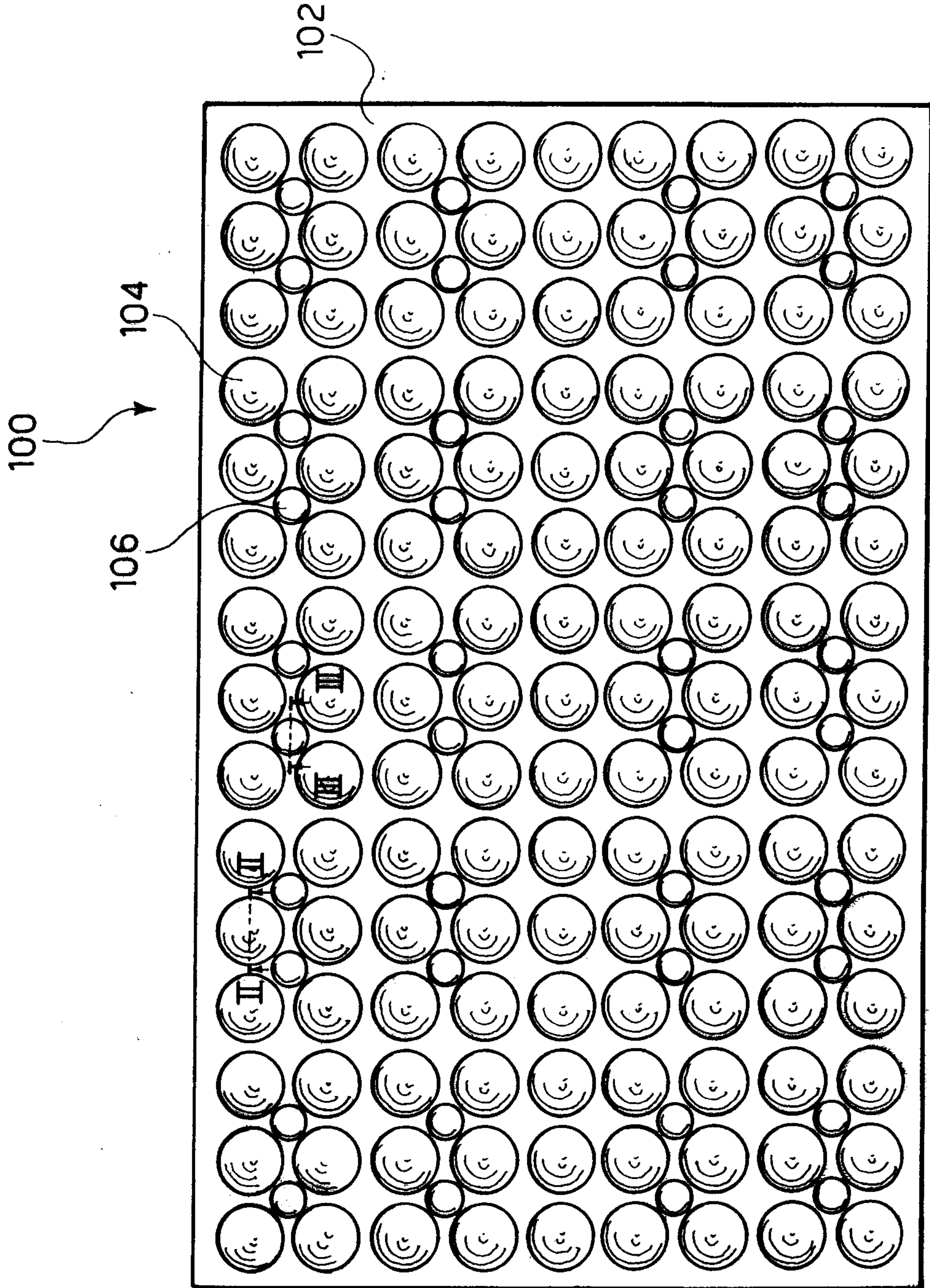


Fig. 2

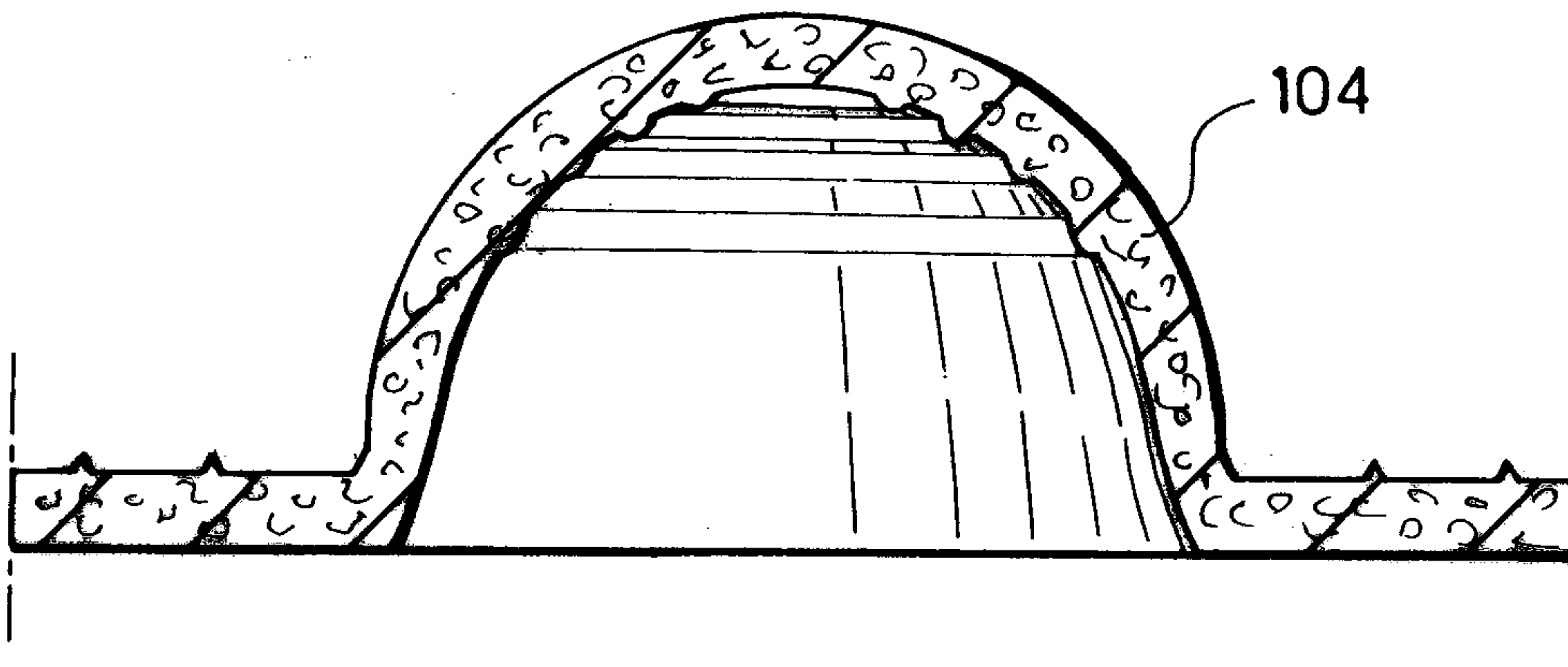
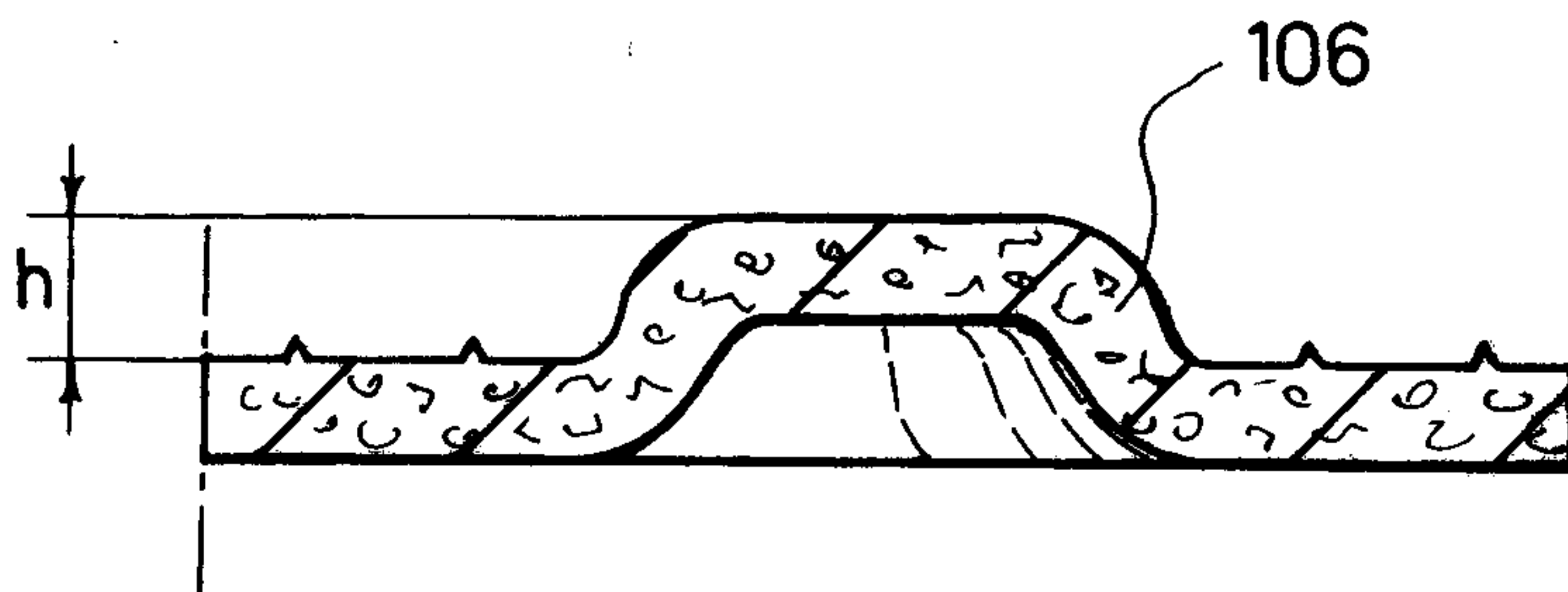


Fig. 3



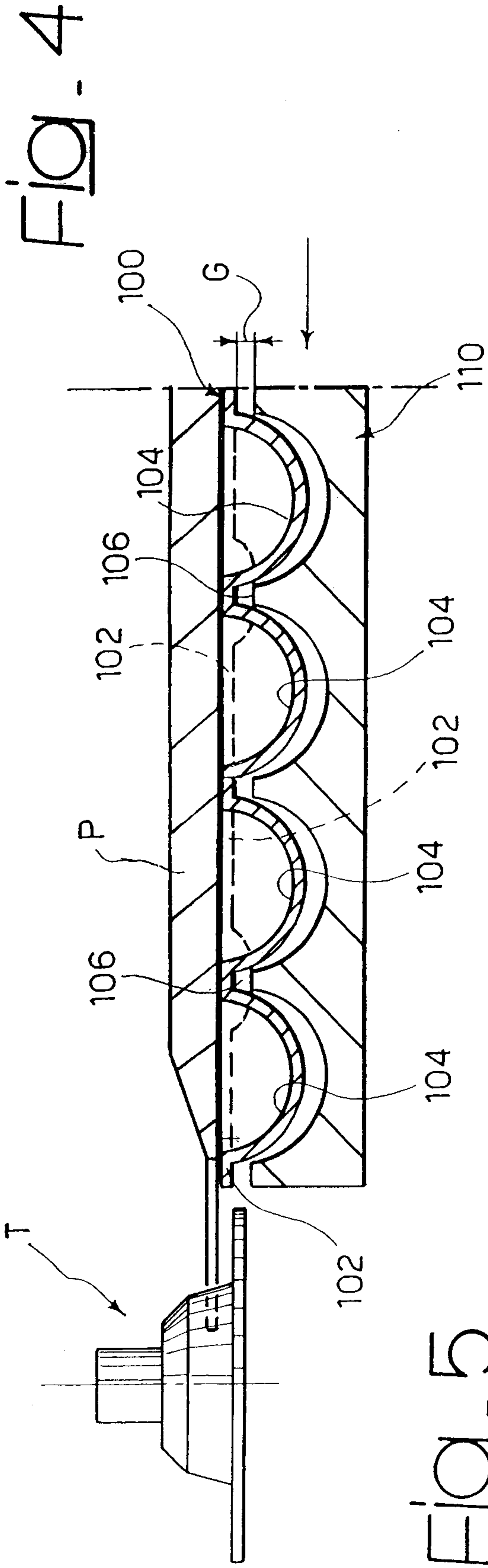


Fig. 5

